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Application Number	09928737
Filing Date	2001-08-13
First Named Inventor	QUAN, SON KY
Art Unit	2831
Examiner Name	NGO, HUNG V.
Attorney Docket Number	SC09785T-CD1

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/HN/	1	NGUYEN, L.T., et al., "Leadframe Designs for Minimum Molding-Induced Warpage," Electronic Components and Technology Conference, 1994, Proceedings., 44th, pgs. 513-520	<input type="checkbox"/>
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